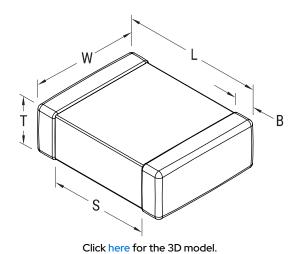


C2220C273F5TACTU

Aliases (C2220C273F5TAC7800)

SMD Comm X8G HT150C, Ceramic, 0.027 uF, 1%, 50 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 2220, 3.5 mm



General Information		
Series	SMD Comm X8G HT150C	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	190 mg	
Shelf Life	78 Weeks	
MSL	1	

0.027 uF

1 kHz 1.0Vrms

Dimensions	
Chip Size	2220
L	5.7mm +/-0.4mm
W	5mm +/-0.4mm
Т	1.4mm +/-0.15mm
S	3.5mm MIN
В	0.6mm +/-0.35mm

W	5mm +/-0.4mm
Т	1.4mm +/-0.15mm
S	3.5mm MIN
В	0.6mm +/-0.35mm
Packaging Specifications	

W	5mm +/-0.4mm	Tolerance	1%
Т	1.4mm +/-0.15mm	Voltage DC	50 VDC
S	3.5mm MIN	Dielectric Withstanding Voltage	125 VDC
В	0.6mm +/-0.35mm	Temperature Range	-55/+150°C
		Temp. Coefficient	X8G
Packaging Specifications		Capacitance Change with	30 ppm/C, 1kHz 1.0Vrms
Packaging	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	
Packaging Quantity 1000	1000	Dissipation Factor	0.1% 1 kHz 1.0Vrms
		Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
		Insulation Resistance	37.037 GOhms

Specifications

Measurement Condition

Capacitance

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